

EB 25 Bump Tip Exposure Agent Product Datasheet

High Process Yield
Low Cost Ownership
Easy Handling Process

Description

EB 25 is a bump tip exposure agent for wafer-level underfill, which can be used by spin coating, or printing method. EB 25 should be used with YINCAE WL 125 wafer-level underfill or WL 125F filled wafer-level underfill together. EB 25 should be applied after applying the wafer-level underfill process. It can be dried at room temperature after applying. EB 25 can provide 100% bump tip exposure and eliminate the interference of underfill on the bump soldering process.

Typical Physical Properties

Product Name	EB 25 Bump Tip Exposure Agent
PROPERTIES OF UNCURED MATERIAL	
Appearance	Transparent colorless liquid
Specific Gravity (ASTM D 1475-60)	0.85 – 0.95 g/cc
Viscosity (DIN CUP 4)	5 – 10s
Extractable Ions (MIL-STD-883E)	
K+	<5ppm
F-	<5ppm
Cl-	<10ppm

Recommended Curing Conditions

EB 25 can be dried at room temperature.

Storage & Shelf Life

6 months provided materials are kept in sealed original container at room temperature. Storage beyond this period can produce higher viscosity. Protect from UV light, moisture, evaporation and foreign materials. Process ability of these products can be adversely affected by evaporation and contamination.

Safety

EB 25 is a friendly, non-toxic material. However, general hygiene practice is recommended when handling this material. For detailed information please consult the product SDS.

Package

EB 25 bump tip exposure agent is available in a one-gallon package. Other packages are available depending on the customer's request. Contact YINCAE for order information.